

ABSTRACT

An object of the present invention is to improve the mechanical strength of a sputtering target, and in order to
5 achieve such an object, there is provided a sputtering target material including: in at.%, 10 to 50% of B; 0 to 20% in total of one or more elements selected from Ti, Zr, Hf, V, Nb, Ta, Cr, Mo, W, Mn, Re, Ru, Rh, Ir, Ni, Pd, Pt, Cu, and Ag; and the balance of
10 at least one of Co and Fe, and unavoidable impurities, in which a hydrogen content is 20 ppm or less.

[NO FIG.]